

ELECTRO-OPTICAL CHARACTERISTICS $T_A=25^{\circ}\text{C}$ $I_f=10\text{mA}$

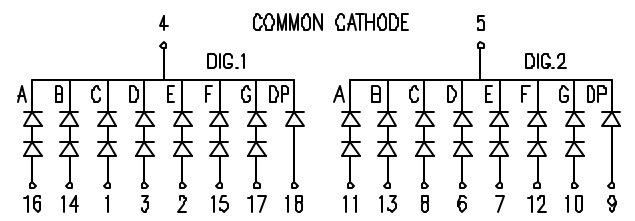
| PARAMETER | MIN | TYP | MAX | UNITS | TEST COND |
|-------------------|----------------------|---------|---------|----------------|----------------------|
| PEAK WAVELENGTH | | 585 | | nm | |
| FORWARD VOLTAGE * | | 2.1/4.2 | 2.5/5.0 | V_f | |
| REVERSE VOLTAGE | 5.0 | | | V_r | $I_r=100\mu\text{A}$ |
| AXIAL INTENSITY | | 2500 | | μcd | $I_f=10\text{mA}$ |
| EMITTED COLOR: | YELLOW | | | | |
| FACE COLOR: | GRAY | | | | |
| SEGMENT COLOR: | MILKY WHITE DIFFUSED | | | | |

* FIRST VALUE FOR SINGLE CHIP IN DECIMAL POINT.

LIMITS OF SAFE OPERATION AT 25°C PER DIE

| PARAMETER | MAX | UNITS |
|--------------------------|------------|------------|
| PEAK FORWARD CURRENT* | 150 | mA |
| STEADY CURRENT | 30 | mA |
| POWER DISSIPATION | 105 | mW |
| DERATE FROM 25°C | -1.2 | mW/°C |
| OPERATING, STORAGE TEMP. | -40 TO +85 | °C |
| SOLDERING TEMP. | +260 | °C |
| 2.0mm FROM BODY | | 3 SEC. MAX |

* $t < 10\mu\text{s}$



*UNLESS OTHERWISE SPECIFIED TOLERANCES PER DECIMAL PRECISION ARE: X=±1 (±0.039), X.X=±0.5 (±0.020), X.XX=±0.25 (±0.010), X.XXX=±0.127 (±0.005). LEAD SIZE=±0.05 (±0.002), LEAD LENGTH=±0.75 (±0.030). MIN=+0.00 -0.00 DECIMAL PRECISION MAX.=+0.00 -0.00 DECIMAL PRECISION

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| REV. | PART NUMBER LDD-CA103RI |
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1.00" SEVEN SEGMENT, DUAL DIGIT DISPLAY,
585nm YELLOW, GRAY FACE, WHITE SEGMENTS,
COMMON CATHODE, RIGHT DECIMAL PLACES.

RELIABILITY NOTE
OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.

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| | | | SCALE: N/A |